

ABSTRACT OF THE DISCLOSURE

[0028]

The present invention provides a method and an apparatus for evaluating the surfaces of substrates for three dimensional defects. The present invention uses low angled lighting positioned on opposite sides of the substrate. A camera, positioned above the substrate captures two images thereof, one using the first light source, one using the second. The first and second images are subtracted from one another to create a third image. Camera data suggestive of three dimensional features is emphasized by subtracting the two images and can be evaluated. A fourth image may be created by selecting the minimum values between the first and second images on a point by point basis. The fourth image also provides useful information in evaluating three dimensional defects.